CD4541B

TEXAS INSTRUMENTS

Data sheet acquired from Harris Semiconductor
SCHS085

CMOS Programmable Timer
High Voltage Types (20V Rating)

Features

- **Low Symmetrical Output Resistance, Typically 100Ω at V_{DD} = 15V**
- **Built-In Low-Power RC Oscillator**
- **Oscillator Frequency Range . . . . . DC to 100kHz**
- **External Clock (Applied to Pin 3) can be Used Instead of Oscillator**
- **Operates as 2^N Frequency Divider or as a Single-Transition Timer**
- **Q/$\overline{Q}$ Select Provides Output Logic Level Flexibility**
- **AUTO or MASTER RESET Disables Oscillator During Reset to Reduce Power Dissipation**
- **Operates With Very Slow Clock Rise and Fall Times**
- **Capable of Driving Six Low Power TTL Loads, Three Low-Power Schottky Loads, or Six HTL Loads Over the Rated Temperature Range**
- **Symmetrical Output Characteristics**
- **100% Tested for Quiescent Current at 20V**
- **5V, 10V, and 15V Parametric Ratings**
- **Meets All Requirements of JEDEC Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"**

Ordering Information

PART NUMBER	TEMP. RANGE (^oC)	PACKAGE	PKG. NO.
CD4541BF	-55 to 125	14 Ld CERDIP	F14.3
CD4541BE	-55 to 125	14 Ld PDIP	E14.3
CD4541BH	-55 to 125	Chip	-
CD4541BM	-55 to 125	14 Ld SOIC	M14.15

Description

CD4541B programmable timer consists of a 16-stage binary counter, an oscillator that is controlled by external R-C components (2 resistors and a capacitor), an automatic power-on reset circuit, and output control logic. The counter increments on positive-edge clock transitions and can also be reset via the MASTER RESET input.

The output from this timer is the Q or $\overline{Q}$ output from the 8th, 10th, 13th, or 16th counter stage. The desired stage is chosen using time-select inputs A and B (see Frequency Select Table). The output is available in either of two modes selectable via the MODE input, pin 10 (see Truth Table). When this MODE input is a logic "1", the output will be a continuous square wave having a frequency equal to the oscillator frequency divided by 2^N. With the MODE input set to logic "0" and after a MASTER RESET is initiated, the output (assuming Q output has been selected) changes from a low to a high state after 2^{N-1} counts and remains in that state until another MASTER RESET pulse is applied or the MODE input is set to a logic "1".

Timing is initialized by setting the AUTO RESET input (pin 5) to logic "0" and turning power on. If pin 5 is set to logic "1", the AUTO RESET circuit is disabled and counting will not start until after a positive MASTER RESET pulse is applied and returns to a low level. The AUTO RESET consumes an appreciable amount of power and should not be used if low-power operation is desired. For reliable automatic power-on reset, V_{DD} should be greater than 5V.

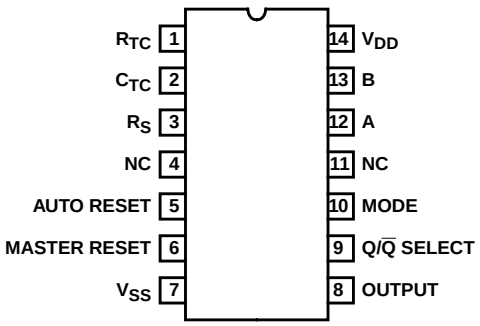
The RC oscillator, shown in Figure 2, oscillates with a frequency determined by the RC network and is calculated using:

$$f = \frac{1}{2.3\ R_{TC}C_{TC}}$$

Where f is between 1kHz and 100kHz and $R_S \geq 10k\Omega$ and $\approx 2R_{TC}$

Pinout

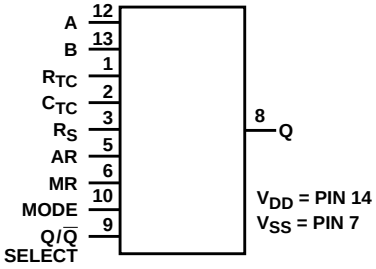
CD4541B (CERDIP, PDIP, SOIC)
TOP VIEW



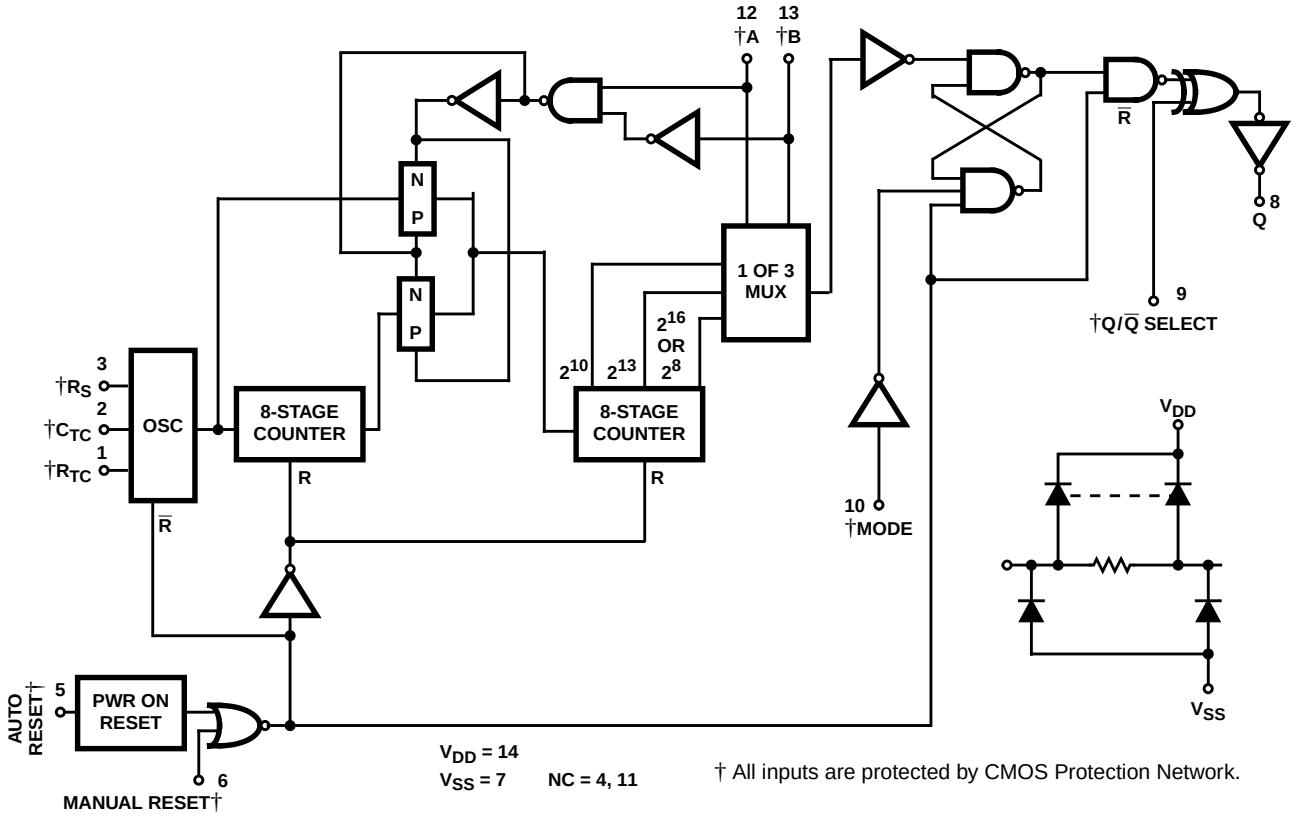
CAUTION: These devices are sensitive to electrostatic discharge. Users should follow proper IC Handling Procedures.

File Number **1378.1**

Functional Diagram



Functional Block Diagram



† All inputs are protected by CMOS Protection Network.

FIGURE 1.

FREQUENCY SELECTION TABLE

A	B	NO. OF STAGES N	COUNT 2^N
0	0	13	8192
0	1	10	1024
1	0	8	256
1	1	16	65536

TRUTH TABLE

PIN	STATE	
	0	1
5	Auto Reset On	Auto Reset Disable
6	Master Reset Off	Master Reset On
9	Output Initially Low After Reset (Q)	Output Initially High After Reset ($\overline{Q}$)
10	Single Transition Mode	Recycle Mode

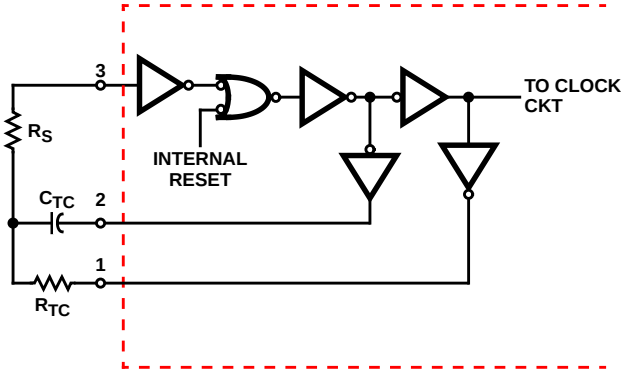


FIGURE 2. RC OSCILLATOR CIRCUIT

Absolute Maximum Ratings

DC Supply - Voltage Range, V_{DD}
Voltages Referenced to V_{SS} Terminal . . . . . -0.5V to +20V
Input Voltage Range, All Inputs . . . . . -0.5V to V_{DD} +0.5V
DC Input Current, Any One Input . . . . . ±10mA
Device Dissipation Per Output Transistor
For T_A = Full Package Temperature Range
(All Package Types) 100mW

Operating Conditions

Temperature Range T_A . . . . . -55°C to 125°C
Supply Voltage Range
For T_A = Full Package Temperature Range . . . . . 3V (Min), 18V (Typ)

Thermal Information

Thermal Resistance (Typical, Note 1)	θ_{JA} (°C/W)	θ_{JC} (°C/W)
PDIP Package	90	N/A
CERDIP Package	90	36
SOIC Package	120	N/A

Maximum Junction Temperature (Plastic Package) . . . . . 150°C
Maximum Storage Temperature Range (T_{STG}) . . . -65°C to 150°C
Maximum Lead Temperature (Soldering 10s)
At Distance 1/16in ± 1/32in (1.59mm ±0.79mm)
from case for 10s Maximum . . . . . 265°C
(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications

PARAMETER	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
								25			
	V_O (V)	V_{IN} (V)	V_{DD} (V)	-55	-40	85	125	MIN	TYP	MAX	
Quiescent Device Current, (Note 2) I_{DD} (Max)	-	0, 5	5	5	5	150	150	-	0.04	5	µA
	-	0, 10	10	10	10	300	300	-	0.04	10	µA
	-	0, 15	15	20	20	600	600	-	0.04	20	µA
	-	0, 20	20	100	100	3000	3000	-	0.08	100	µA
Output Low (Sink) Current I_{OL} (Min)	0.4	0, 5	5	1.9	1.85	1.26	1.08	1.55	3.1	-	µA
	0.5	0, 10	10	5	4.8	3.3	2.8	4	8	-	µA
	1.5	0, 15	15	12.6	12	8.4	7.2	10	20	-	µA
Output High (Source) Current, I_{OH} (Min)	4.6	0, 5	5	-1.9	-1.85	-1.26	-1.08	-1.55	-3.1	-	mA
	2.5	0, 5	5	-6.2	-6	-4.1	-3	-5	-10	-	mA
	9.5	0, 10	10	-5	-4.8	-3.3	-2.8	-4	-8	-	mA
	13.5	0, 15	15	-12.6	-12	-8.4	-7.2	-10	-20	-	mA
Output Voltage: Low-Level, V_{OL} (Max)	-	0, 5	5	-	0.05			-	0	0.05	mA
	-	0, 10	10	-	0.05			-	0	0.05	mA
	-	0, 15	15	-	0.05			-	0	0.05	mA
Output Voltage: High-Level, V_{OH} (Min)	-	0, 5	5	-	4.95			4.95	5	-	mA
	-	0, 10	10	-	9.95			9.95	10	-	mA
	-	0, 15	15	-	14.95			14.95	15	-	mA
Input Low Voltage, V_{IL} (Max)	0.5, 4.5	-	5	-	1.5			-	-	1.5	V
	1, 9	-	10	-	3			-	-	3	V
	1.5, 13.5	-	15	-	4			-	-	4	V

Electrical Specifications (Continued)

PARAMETER	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (^{o}C)							UNITS
								25			
	V_O (V)	V_{IN} (V)	V_{DD} (V)	-55	-40	85	125	MIN	TYP	MAX	
Input High Voltage, V_{IH} (Min)	0.5, 4.5	-	5	-		3.5		3.5	-	-	V
	1, 9	-	10	-		7		7	-	-	V
	1.5, 13.5	-	15	-		11		11	-	-	V
Input Current, I_{IN} (Max)	-	0, 18	18	±0.1	±0.1	±1	±1	-	$\pm 10^{-5}$	±0.1	µA

NOTE:

2. With AUTO RESET enabled, additional current drain at 25^{o}C is:
   7µA (Typ), 200µA (Max) at 5V;
   30µA (Typ), 350µA (Max) at 10V;
   80µA (Typ), 500µA (Max) at 15V

Dynamic Electrical Specifications

$T_A = 25^{o}C$, Input t_r, t_f = 20ns, C_L = 50pF, R_L = 200kΩ

PARAMETER	SYMBOL	V_{DD} (V)	MIN	TYP	MAX	UNITS
Propagation Delay Times Clock to Q	(2^8) t_{PHL}, t_{PLH}	5	-	3.5	10.5	µs
		10	-	1.25	3.8	µs
		15	-	0.9	2.9	µs
	(2^{16}) t_{PHL}, t_{PLH}	5	-	6.0	18	µs
		10	-	3.5	10	µs
		15	-	2.5	7.5	µs
Transition Time	t_{THL}	5	-	100	200	ns
		10	-	50	100	ns
		15	-	40	80	ns
	t_{THL}	5	-	180	360	ns
		10	-	90	180	ns
		15	-	65	130	ns
MASTER RESET, CLOCK Pulse Width		5	900	300	-	ns
		10	300	100	-	ns
		15	225	85	-	ns
Maximum Clock Pulse Input Frequency	f_{CL}	5	-	1.5	-	MHz
		10	-	4	-	MHz
		15	-	6	-	MHz
Maximum Clock Pulse Input Rise or Fall time	t_r, t_f	5, 10, 15	Unlimited			µs

Digital Timer Application

A positive pulse on MASTER RESET resets the counters and latch. The output goes high and remains high until the number of pulses, selected by A and B, are counted. This circuit is retriggerable and is as accurate as the input frequency. If additional accuracy is desired, an external clock can be used on pin 3. A setup time equal to the width of the one-shot output is required immediately following initial power up, during which time the output will be high.

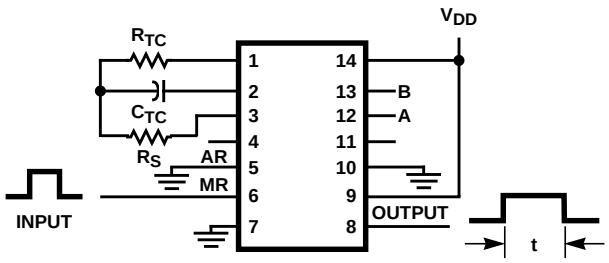
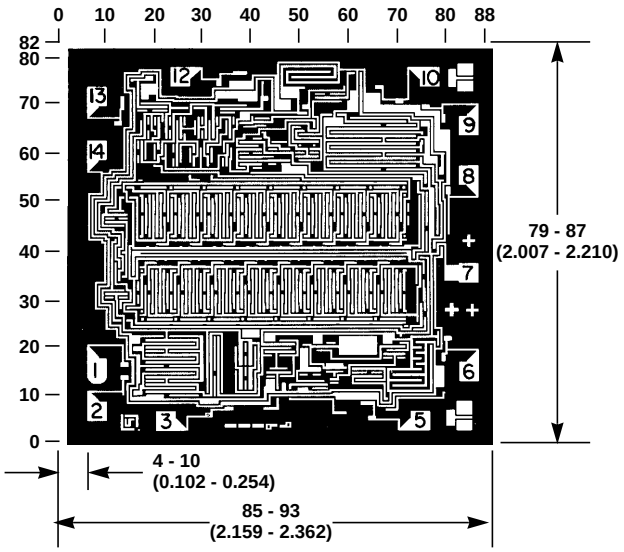


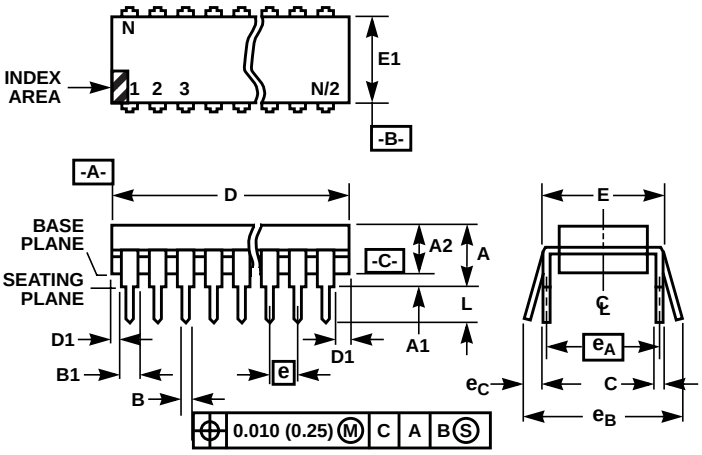
FIGURE 3. DIGITAL TIMER APPLICATION CIRCUIT



NOTE: Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

FIGURE 4. DIMENSIONS AND PAD LAYOUT FOR CD4541B

Dual-In-Line Plastic Packages (PDIP)



NOTES:

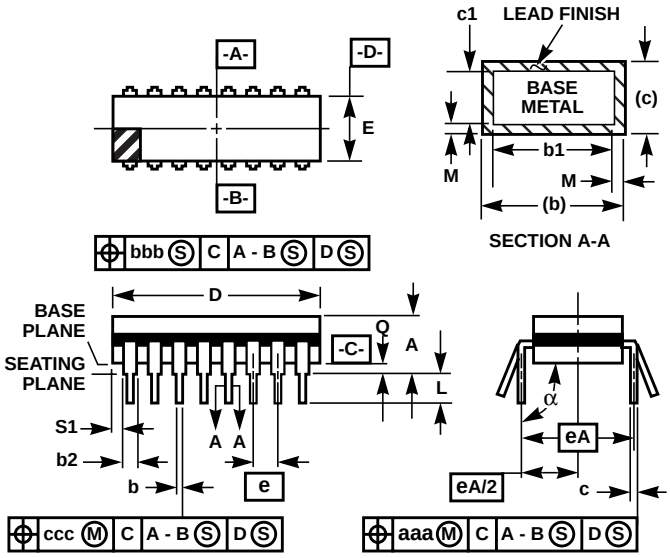
1. Controlling Dimensions: INCH. In case of conflict between English and Metric dimensions, the inch dimensions control.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Symbols are defined in the "MO Series Symbol List" in Section 2.2 of Publication No. 95.
4. Dimensions A, A1 and L are measured with the package seated in JEDEC seating plane gauge GS-3.
5. D, D1, and E1 dimensions do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 inch (0.25mm).
6. E and e_A are measured with the leads constrained to be perpendicular to datum -C-.
7. e_B and e_C are measured at the lead tips with the leads unconstrained. e_C must be zero or greater.
8. B1 maximum dimensions do not include dambar protrusions. Dambar protrusions shall not exceed 0.010 inch (0.25mm).
9. N is the maximum number of terminal positions.
10. Corner leads (1, N, N/2 and N/2 + 1) for E8.3, E16.3, E18.3, E28.3, E42.6 will have a B1 dimension of 0.030 - 0.045 inch (0.76 - 1.14mm).

E14.3 (JEDEC MS-001-AA ISSUE D)
14 LEAD DUAL-IN-LINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.210	-	5.33	4
A1	0.015	-	0.39	-	4
A2	0.115	0.195	2.93	4.95	-
B	0.014	0.022	0.356	0.558	-
B1	0.045	0.070	1.15	1.77	8
C	0.008	0.014	0.204	0.355	-
D	0.735	0.775	18.66	19.68	5
D1	0.005	-	0.13	-	5
E	0.300	0.325	7.62	8.25	6
E1	0.240	0.280	6.10	7.11	5
e	0.100 BSC		2.54 BSC		-
e_A	0.300 BSC		7.62 BSC		6
e_B	-	0.430	-	10.92	7
L	0.115	0.150	2.93	3.81	4
N	14		14		9

Rev. 0 12/93

Ceramic Dual-In-Line Frit Seal Packages (CERDIP)



NOTES:

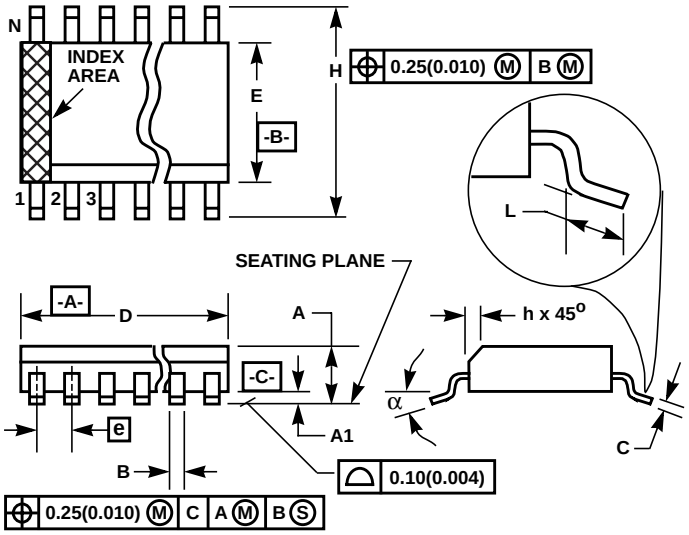
1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
2. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
3. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness.
4. Corner leads (1, N, N/2, and N/2+1) may be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b2.
5. This dimension allows for off-center lid, meniscus, and glass overrun.
6. Dimension Q shall be measured from the seating plane to the base plane.
7. Measure dimension S1 at all four corners.
8. N is the maximum number of terminal positions.
9. Dimensioning and tolerancing per ANSI Y14.5M - 1982.
10. Controlling dimension: INCH.

F14.3 MIL-STD-1835 GDIP1-T14 (D-1, CONFIGURATION A)
14 LEAD CERAMIC DUAL-IN-LINE FRIT SEAL PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	-	0.200	-	5.08	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
c	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	0.785	-	19.94	5
E	0.220	0.310	5.59	7.87	5
e	0.100 BSC		2.54 BSC		-
eA	0.300 BSC		7.62 BSC		-
eA/2	0.150 BSC		3.81 BSC		-
L	0.125	0.200	3.18	5.08	-
Q	0.015	0.060	0.38	1.52	6
S1	0.005	-	0.13	-	7
α	90^o	105^o	90^o	105^o	-
aaa	-	0.015	-	0.38	-
bbb	-	0.030	-	0.76	-
ccc	-	0.010	-	0.25	-
M	-	0.0015	-	0.038	2, 3
N	14		14		8

Rev. 0 4/94

Small Outline Plastic Packages (SOIC)



NOTES:

1. Symbols are defined in the “MO Series Symbol List” in Section 2.2 of Publication Number 95.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension “D” does not include mold flash, protrusions or gate burrs. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
4. Dimension “E” does not include interlead flash or protrusions. Interlead flash and protrusions shall not exceed 0.25mm (0.010 inch) per side.
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the crosshatched area.
6. “L” is the length of terminal for soldering to a substrate.
7. “N” is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. The lead width “B”, as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch).
10. Controlling dimension: MILLIMETER. Converted inch dimensions are not necessarily exact.

M14.15 (JEDEC MS-012-AB ISSUE C)
14 LEAD NARROW BODY SMALL OUTLINE PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.0532	0.0688	1.35	1.75	-
A1	0.0040	0.0098	0.10	0.25	-
B	0.013	0.020	0.33	0.51	9
C	0.0075	0.0098	0.19	0.25	-
D	0.3367	0.3444	8.55	8.75	3
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		-
H	0.2284	0.2440	5.80	6.20	-
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	14		14		7
α	0^o	8^o	0^o	8^o	-

Rev. 0 12/93

IMPORTANT NOTICE

Texas Instruments and its subsidiaries (TI) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current and complete. All products are sold subject to the terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

TI warrants performance of its semiconductor products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are utilized to the extent TI deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

CERTAIN APPLICATIONS USING SEMICONDUCTOR PRODUCTS MAY INVOLVE POTENTIAL RISKS OF DEATH, PERSONAL INJURY, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE ("CRITICAL APPLICATIONS"). TI SEMICONDUCTOR PRODUCTS ARE NOT DESIGNED, AUTHORIZED, OR WARRANTED TO BE SUITABLE FOR USE IN LIFE-SUPPORT DEVICES OR SYSTEMS OR OTHER CRITICAL APPLICATIONS. INCLUSION OF TI PRODUCTS IN SUCH APPLICATIONS IS UNDERSTOOD TO BE FULLY AT THE CUSTOMER'S RISK.

In order to minimize risks associated with the customer's applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards.

TI assumes no liability for applications assistance or customer product design. TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right of TI covering or relating to any combination, machine, or process in which such semiconductor products or services might be or are used. TI's publication of information regarding any third party's products or services does not constitute TI's approval, warranty or endorsement thereof.